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March 2001 Revised January 2005

NC7WZ125

TinyLogic® UHS Dual Buffer with 3-STATE Outputs

General Description

The NC7WZ125 is a Dual Non-Inverting Buffer with independent active LOW enables for the 3-STATE outputs. The Ultra High Speed device is fabricated with advanced CMOS technology to achieve superior switching performance with high output drive while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over the 1.65V to 5.5V $V_{\rm CC}$ operating range. The inputs and outputs are high impedance when V_{CC} is 0V. Inputs tolerate voltages up to 5.5V independent of V_{CC} operating range. Outputs tolerate voltages above V_{CC} when in the 3-STATE condition.

Features

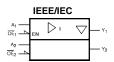
- Space saving US8 surface mount package
- MicroPak™ Pb-Free leadless package
- Ultra High Speed; t_{PD} 2.6 ns typ into 50 pF at 5V V_{CC}
- High Output Drive; ±24 mA at 3V V_{CC}
- Broad V_{CC} Operating Range; 1.65V to 5.5V
- Matches the performance of LCX when operated at $3.3V V_{CC}$
- Power down high impedance inputs/outputs
- Overvoltage tolerant inputs facilitate 5V to 3V translation
- Outputs are overvoltage tolerant in 3-STATE mode
- Proprietary noise/EMI reduction circuitry implemented

Ordering Code:

Order Number	Package Number	Product Code Top Mark	Package Description	Supplied As
NC7WZ125K8X	MAB08A	WZ25	8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide	3k Units on Tape and Reel
NC7WZ125L8X	MAC08A	P3	Pb-Free 8-Lead MicroPak, 1.6 mm Wide	5k Units on Tape and Reel

Pb-Free package per JEDEC J-STD-020B.

Logic Symbol



Pin Descriptions

Pin Names	Description
ŌE _n	Enable Inputs for 3-STATE Outputs
A _n	Input
Y _n	3-STATE Outputs

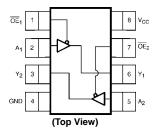
Function Table

H = HIGH Logic Level

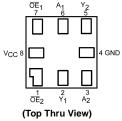
Inp	Output	
OE	A _n	Y _n
L	L	L
L	Н	Н
Н	L	Z
Н	Н	Z

L = LOW Logic Level TinyLogic® is a registered trademark of Fairchild Semiconductor Corporation.

Connection Diagrams



Pad Assignments for MicroPak



 $\label{eq:microPak} \mbox{MicroPak}^{\mbox{\tiny TM}} \mbox{ is a trademark of Fairchild Semiconductor Corporation}.$

Z = 3-STATE

Absolute Maximum Ratings(Note 1)

DC Input Diode Current (I_{IK})

@V_{IN} < 0V -50 n

DC Output Diode Current (I_{OK}) @V_{OUT} < 0V

 $\label{eq:Storage Temperature Range Temperature Range Temperature Under Bias} (T_{J}) & -65^{\circ}\text{C to } +150^{\circ}\text{C} \\ \text{Junction Lead Temperature under Bias} (T_{J}) & +150^{\circ}\text{C} \\ \end{cases}$

Junction Lead Temperature (T_L)

 $\label{eq:soldering} \begin{tabular}{ll} (Soldering, 10 seconds) & +260 ^{\circ} C \\ Power Dissipation (P_D) @ +85 ^{\circ} C & 250 \ mW \\ \end{tabular}$

Recommended Operating Conditions (Note 3)

 $\begin{array}{ll} \mbox{Supply Voltage Operating (V_{CC})} & 1.65\mbox{V to } 5.5\mbox{V} \\ \mbox{Supply Voltage Data Retention (V_{CC})} & 1.5\mbox{V to } 5.5\mbox{V} \\ \mbox{Input Voltage (V_{IN})} & 0\mbox{V to } 5.5\mbox{V} \\ \end{array}$

-50 mA Output Voltage (V_{OUT})

Active State $0V \text{ to } V_{CC}$ 3-STATE 0V to 5.5VOperating Temperature (T_A) $-40^{\circ}C$ to $+85^{\circ}C$

Operating Temperature (T_A)
Input Rise and Fall Time (t_r, t_f)

 $\begin{array}{lll} \text{V}_{\text{CC}} @ \ 1.8\text{V}, \ 0.15\text{V}, \ 2.5\text{V} \pm 0.2\text{V} & 0 \ \text{ns/V} \ \text{to} \ 20 \ \text{ns/V} \\ \text{V}_{\text{CC}} @ \ 3.3\text{V} \pm 0.3\text{V} & 0 \ \text{ns/V} \ \text{to} \ 10 \ \text{ns/V} \\ \text{V}_{\text{CC}} @ \ 5.0\text{V} \pm 0.5\text{V} & 0 \ \text{ns/V} \ \text{to} \ 5 \ \text{ns/V} \\ \end{array}$

Thermal Resistance (θ_{JA}) 250°C/W

Note 1: Absolute maximum ratings are DC values beyond which the device may be damaged or have its useful life impaired. The datasheet specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation outside datasheet specifications.

Note 2: The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

Note 3: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	V _{CC}	$T_A = +25^{\circ}C$		$T_A = -40^{\circ}C$ to $+85^{\circ}C$		Units	Conditions		
Symbol	rarameter	(V)	Min	Тур	Max	Min	Max	Units	Conditions	
V _{IH}	HIGH Level Input Voltage	1.65 to 1.95	0.75 V _{CC}			0.75 V _{CC}		V		
		2.3 to 5.5	0.7 V _{CC}			0.7 V _{CC}		V		
V _{IL}	LOW Level Input Voltage	1.65 to 1.95			0.25 V _{CC}		0.25 V _{CC}	V		
		2.3 to 5.5			0.3 V _{CC}		0.3 V _{CC}	V		
V _{OH}	HIGH Level Output Voltage	1.65	1.55	1.65		1.55				
		2.3	2.2	2.3		2.2		V	$V_{IN}=V_{IH} \\$	$I_{OH} = -100~\mu A$
		3.0	2.9	3.0		2.9		V	or V _{IL}	
		4.5	4.4	4.5		4.4				
		1.65	1.29	1.52		1.29				$I_{OH} = -4 \text{ mA}$
		2.3	1.9	2.15		1.9			$V_{IN} = V_{IH} \\$	$I_{OH} = -8 \text{ mA}$
		3.0	2.4	2.80		2.4		V	or V _{IL}	$I_{OH} = -16 \text{ mA}$
		3.0	2.3	2.68		2.3				$I_{OH} = -24 \text{ mA}$
		4.5	3.8	4.20		3.8				$I_{OH} = -32 \text{ mA}$
V _{OL}	LOW Level Output Voltage	1.65		0.0	0.10		0.10			
		2.3		0.0	0.10		0.10	V	$V_{IN} = V_{IH}$	$I_{OL} = 100 \mu A$
		3.0		0.0	0.10		0.10	V	or V _{IL}	
		4.5		0.0	0.10		0.10			
		1.65		0.08	0.24		0.24			$I_{OL} = 4 \text{ mA}$
		2.3		0.10	0.3		0.3			$I_{OL} = 8 \text{ mA}$
		3.0		0.15	0.4		0.4	V		$I_{OL} = 16 \text{ mA}$
		3.0		0.22	0.55		0.55			$I_{OL} = 24 \text{ mA}$
		4.5		0.22	0.55		0.55			$I_{OL} = 32 \text{ mA}$
I _{IN}	Input Leakage Current	0 to 5.5			±0.1		±1	μΑ	$V_{IN} = 5.5V$, GND
I _{OZ}	3-STATE Output Leakage	1.65 to 5.5			±0.5		±5	μΑ	$V_{IN} = V_{IH}$	or V _{IL}
									$0 \le V_{OUT}$	≤ 5.5V
I _{OFF}	Power Off Leakage Current	0.0			1		10	μΑ	V _{IN} or V _{OI}	_{JT} = 5.5V
I _{CC}	Quiescent Supply Current	1.65 to 5.5			1		10	μΑ	$V_{IN} = 5.5V$, GND

Noise Characteristics

Symbol	Parameter	V _{CC} T _A = + 25°C		Units	Conditions	
Cynnbon	i didilicio	(V)	Тур	Max	Onito	Conditions
V _{OLP} (Note 4)	Quiet Output Maximum Dynamic V _{OL}	5.0		1.0	V	C _L = 50 pF
V _{OLV} (Note 4)	Quiet Output Minimum Dynamic V _{OL}	5.0		1.0	V	C _L = 50 pF
V _{OHV} (Note 4)	Quiet Output Minimum Dynamic V _{OH}	5.0		4.0	V	C _L = 50 pF
V _{IHD} (Note 4)	Minimum HIGH Level Dynamic Input Voltage	5.0		3.5	V	C _L = 50 pF
V _{ILD} (Note 4)	Maximum LOW Level Dynamic Input Voltage	5.0		1.5	V	C _L = 50 pF

Note 4: Parameter guaranteed by design.

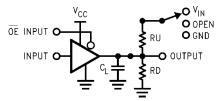
AC Electrical Characteristics

Symbol	Parameter	v _{cc}	$T_A = +25^{\circ}C$			$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		Units	Conditions	Figure
Symbol	raiametei	(V)	Min	Тур	Max	Min	Max	Units	Conditions	Number
t _{PLH} ,	Propagation Delay	1.8 ± 0.15	2.0		12.0	2.0	13.0		C _L = 15 pF	
t _{PHL}	A _N to Y _N	2.5 ± 0.2	1.0		7.5	1.0	8.0	ns	$R_D = 1 M\Omega$	Figures
		3.3 ± 0.3	0.8		5.2	0.8	5.5	115	S1= Open	1, 3
		5.0 ± 0.5	0.5		4.5	0.5	4.8			
t _{PLH} ,	Propagation Delay	3.3 ± 0.3	1.2		5.7	1.2	6.0		C _L = 50 pF	F:
t _{PHL}	A _N to Y _N	5.0 ± 0.5	0.8		5.0	0.8	5.3	ns	$R_D = 500\Omega$	Figures 1, 3
									S1= Open	., -
t _{OSLH} ,	Output to Output Skew	3.3 ± 0.3			1.0		1.0		C _L = 50 pF	F:
toshl	(Note 5)	5.0 ± 0.5			0.8		0.8	ns	$R_D = 500\Omega$	Figures 1, 3
									S1= Open	., -
t _{PZL} ,	Output Enable Time	1.8 ± 0.15	3.0		14.0	3.0	15.0		C _L = 50 pF	
t _{PZH}		2.5 ± 0.2	1.8		8.5	1.8	9.0		R_D , $R_U = 500 \Omega$	
		3.3 ± 0.3	1.2		6.2	1.2	6.5	ns	$S1 = GND$ for t_{PZH}	
		5.5 ± 0.5	0.8		5.5	0.8	5.8		$S1 = V_I \text{ for } t_{PZL}$	1, 3
									$V_I = 2 \times V_{CC}$	
t _{PLZ} ,	Output Disable Time	1.8 ± 0.15	2.5		12.0	2.5	13.0		C _L = 50 pF	
t_{PHZ}		2.5 ± 0.2	1.5		8.0	1.5	8.5		R_D , $R_U = 500 \Omega$	
		3.3 ± 0.3	0.8		5.7	0.8	6.0	ns	$S1 = GND$ for t_{PZH}	Figures 1, 3
		5.0 ± 0.5	0.3		4.7	0.3	5.0		$S1 = V_I \text{ for } t_{PZL}$., -
									$V_I = 2 \times V_{CC}$	
C _{IN}	Input Capacitance	0		2.5				pF		
C _{OUT}	Output Capacitance	5.0		4				Pi		
C _{PD}	Power Dissipation Capacitance	3.3		10				pF	(Note 6)	Figure 2
		5.0		12				Pi	(14016-0)	i igule 2

 $\textbf{Note 5: Parameter guaranteed by design. } t_{OSLH} = |t_{PLHmax} - t_{PLHmin}|; t_{OSHL} = |t_{PHLmax} - t_{PHLmin}|.$

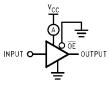
Note 6: C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (See Figure 2.) C_{PD} is related to I_{CCD} dynamic operating current by the expression: $I_{CCD} = (C_{PD})(V_{CC})(f_{|N}) + (I_{CC}static)$.

AC Loading and Waveforms



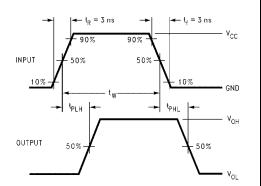
 ${
m C_L}$ includes load and stray capacitance Input PRR = 1.0 MHz; ${
m t_w}$ = 500 ns

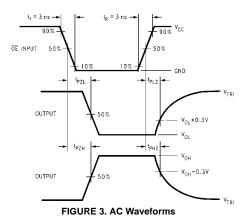
FIGURE 1. AC Test Circuit



 $\begin{aligned} & \text{Input} = \text{AC Waveform; } t_{\text{r}} = t_{\text{f}} = 1.8 \text{ ns;} \\ & \text{PRR} = 10 \text{ MHz; } \text{Duty Cycle} = 50\% \end{aligned}$

FIGURE 2. I_{CCD} Test Circuit



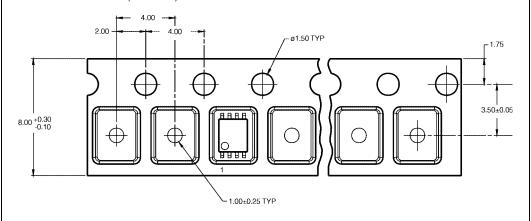


Tape and Reel Specification

Tape Format for US8

Tape I offiliat for 000							
Package	Таре	Number	Cavity	Cover Tape			
Designator	Section	Cavities	Status	Status			
	Leader (Start End)	125 (typ)	Empty	Sealed			
K8X	Carrier	3000	Filled	Sealed			
	Trailer (Hub End)	75 (typ)	Empty	Sealed			

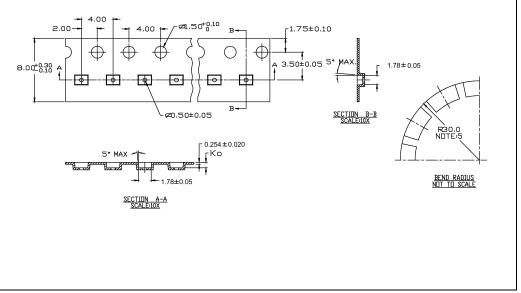
TAPE DIMENSIONS inches (millimeters)



Tape Format for MicroPak

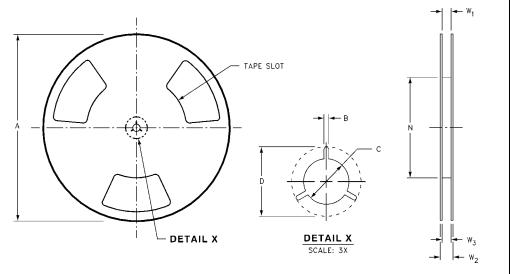
Package	Tape	Number	Cavity	Cover Tape
Designator	Section	Cavities	Status	Status
	Leader (Start End)	125 (typ)	Empty	Sealed
L8X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

TAPE DIMENSIONS inches (millimeters)

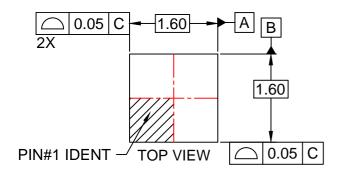


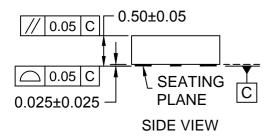
Tape and Reel Specification (Continued)

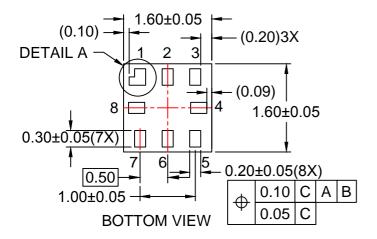
REEL DIMENSIONS inches (millimeters)

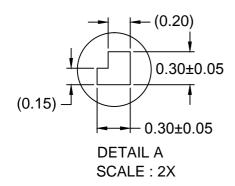


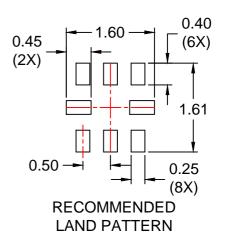
Tape Size	Α	В	С	D	N	W1	W2	W3
0	7.0	0.059	0.512	0.795	2.165	0.331 + 0.059/-0.000	0.567	W1 + 0.078/-0.039
8 mm	(177.8)	(1.50)	(13.00)	(20.20)	(55.00)	(8.40 + 1.50/-0.00)	(14.40)	(W1 + 2.00/-1.00)







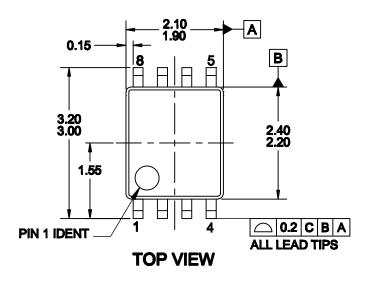


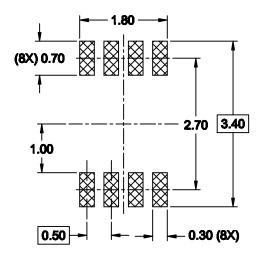


NOTES:

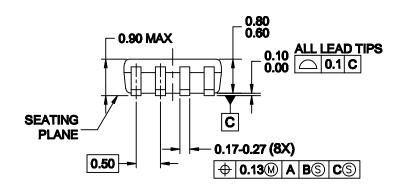
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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-MAC08Arev5.







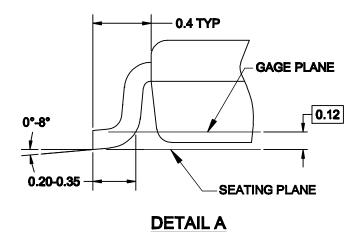
RECOMMENDED LAND PATTERN

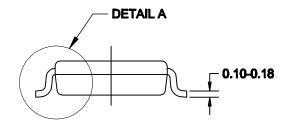


SIDE VIEW

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-187
- **B. DIMENSIONS ARE IN MILLIMETERS.**
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1994.
- E. FILE DRAWING NAME: MKT-MAB08Arev4





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